

What is claimed is:

- 1 1. A laminate support used in the process of wire bonding a circuit device, comprising a closed woven mesh having strands whose separation distance is equal to or less than the diameter of said wire of said circuit device.
- 1 2. The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said separation distance is no greater than 0.7 mils.
- 1 3. The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said separation distance is between 0.2 and 0.7 mils.
- 1 4. The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said laminate support comprises fiberglass.
- 1 5. The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said laminate support is between approximately 2.5 and 4 mils thick.

1 6. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 1, wherein
3 said circuit device is a pad of large scale integrated
4 design.

1 7. A laminate support used in the process of wire
2 bonding a circuit device, comprising a closed woven mesh
3 having warp and weave strands, whose separation distance is
4 equal to or less than the thickness of said wire of said
5 circuit device, as measured lengthwise through said closed
6 woven mesh.

1 8. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 7, wherein
3 said separation distance is equal to or less than 0.7 mils.

1 9. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 7, wherein
3 said separation distance is between 0.2 and 0.7 mils.

1 10. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 7, wherein
3 said laminate support comprises fiberglass.

1 11. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 7, wherein
3 said laminate support is between approximately 2.5 and 4
4 mils thick.

1 12. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 7, wherein
3 said circuit device comprises a pad of large scale
4 integrated design.

1 13. A laminate support used in the process of wire
2 bonding a circuit device, comprising a closed woven mesh
3 having warp and weave strands, whose separation distance is
4 no greater than the diameter of said wire of said circuit
5 device as measured lengthwise through said closed woven
6 mesh, and wherein said separation distance is approximately
7 equal to or less than 0.7 mils.

1 14. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 13,
3 wherein said separation distance is between 0.2 and 0.7
4 mils.

1 15. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 13,
3 wherein said laminate support comprises fiberglass.

1 16. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 13,
3 wherein said laminate support is between approximately 2.5
4 and 4 mils thick.

1 17. The laminate support used in the process of wire
2 bonding a circuit device in accordance with claim 13,
3 wherein said circuit device comprises a pad of large scale
4 integrated design.

1 18. A method for supporting a circuit device during
2 wire bonding, comprising the steps of:

3 a) applying a capillary tool to wire that is to
4 be bonded to a circuit device; and

5 b) supporting said circuit device upon a closed
6 woven mesh whose separation distance between woven strands
7 is less than or equal to a diameter of said wire.

1 19. The method of claim 18, wherein said separation
2 distance is approximately equal to or less than 0.7 mils.

1 20. The method of claim 18, wherein said separation
2 distance is between approximately 0.2 and 0.7 mils.